



Form Type	Distribute	Version	2.0	Ref	IPC 1752A	Sectionals	Manufacturing Info/ Material Info	Subsectionals	D, A
Supplier Information									
Company Name	TE Connectivity	Request Document ID		Contact Name	CC WU	Contact Title	Product Compliance Engineer		
Company Unique ID	TE Connectivity	Response Date	2016-04-22	Contact Email	cc.wu@tycoelectronics.com				
Contact Phone Number	021-33259321								
Legal Statement									
Supplier Acceptance	true								
Legal Statement									
The information provided in this document is based upon reasonable inquiry of our suppliers. This information is subject to change. This information does not in any way modify existing purchase specifications or existing contractual or other agreements terms between TE Connectivity (or its affiliated companies) and its customers.									
Product									
Manufacturer Item number	770233-1	Amount	0.467	Version	-	Identity			
Manufacturer Item Name	CMNL IDC COVER	Weight Uom	g	Mfr Site		Authority			
Date		UOM	Each						
EURoHS-0508	Product(s) meets EU RoHS requirement without any exemptions								
ChinaRoHS-0508	Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products								
EUREACH-0615	REACH Candidate Substances of Very High Concern ARE NOT Yet Reviewed								
Manufacturing Information									
J-STD-020 MSL Rating		Max Total a Wave Time		Ramp Rate		Wave Additional Info			
Classification Temp		Max Wave Solder Time	0.0	Ramp Down Rate		Psi Rating Reflow			
Max Time Within 5		Psi Rating Wave		Package Designator		Size	0.0		
Time Above 217		Reflow Additional Info		Preheat Max Temp		Terminal Base Alloy	NAC		
Preheat Duration		bulk Solder Termination	NAC	Nbr or Reflow Cycles		Terminal Plating	NAC		
Preheat Min Temp		Nbr of Instances	0	Component Temp Spike		Shape	NAC		
Product Disclosure									
Sub-Item/Material/Substance	Level	Name	Substance Category	Substance CAS	Substance Concentration	Quantity	Mass per Unit	UOM	Exemption
Sub-Item	1	Polyester Compound				1.0	0.467	g	
Material	2	PBT				1.0	0.467	g	
Substance	3	Benzenepropionic acid, 3,5-bis(1,1-dimethylethyl)-4-hydroxy-, 1,1-[2,2-bis[[3-[3,5-bis(1,1-dimethylethyl)-4-hydroxyphenyl]-1-oxopropoxy]methyl]-1,3-propanediyl] ester	Supplier	6683-19-8	0.2	1.0	9.34E-4	g	
Substance	3	Ethene, homopolymer	Supplier	9002-88-4	5.0	1.0	0.02335	g	
Substance	3	Ethene, 1,1,2,2-tetrafluoro-, homopolymer	Supplier	9002-84-0	0.1	1.0	4.67E-4	g	
Substance	3	Antimony oxide (Sb2O3)	Supplier	1309-64-4	8.0	1.0	0.03736	g	
Substance	3	7-Oxabicyclo[4.1.0]heptane-3-carboxylic acid, 7-oxabicyclo[4.1.0]hept-3-ylmethyl ester	Supplier	2386-87-0	0.1	1.0	4.67E-4	g	
Substance	3	Phosphoric acid, zinc salt (2:3)	Supplier	7779-90-0	0.5	1.0	0.002335	g	

Substance	3	2-Propenenitrile, polymer with ethenylbenzene	Supplier	9003-54-7	0.1	1.0	4.67E-4	g	
Substance	3	Furan, tetrahydro-	Supplier	109-99-9	0.5	1.0	0.002335	g	
Substance	3	Carbonic dichloride, polymer with 4,4-(1-methylethylidene)bis[2,6-dibromophenol] and 4,4-(1-methylethylidene)bis[phenol], 4-(1-methyl-1-phenylethyl)phenyl ester	Supplier	156042-31-8	30.0	1.0	0.1401	g	
Substance	3	Carbonic dichloride, polymer with 4,4-(1-methylethylidene)bis[phenol], 4-(1-methyl-1-phenylethyl)phenyl ester	Supplier	111211-39-3	5.0	1.0	0.02335	g	
Substance	3	Acetic acid ethenyl ester, polymer with ethene	Supplier	24937-78-8	2.0	1.0	0.00934	g	
Substance	3	Phosphorous acid, decyl diphenyl ester	Supplier	3287-06-7	0.1	1.0	4.67E-4	g	
Substance	3	1,4-Benzenedicarboxylic acid, 1,4-dimethyl ester, polymer with 1,4-butanediol	Supplier	30965-26-5	48.4	1.0	0.226028	g	